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DATE: August 11, 2020

PCN #: 2327 Rev 2 - (Final Notice)

PCN Title: Fab Porting from Global Foundries to MagnaChip, Assembly Site Transfer, and Bond Wire Change

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification and provide us with forecast within 30 days of the date of this PCN. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

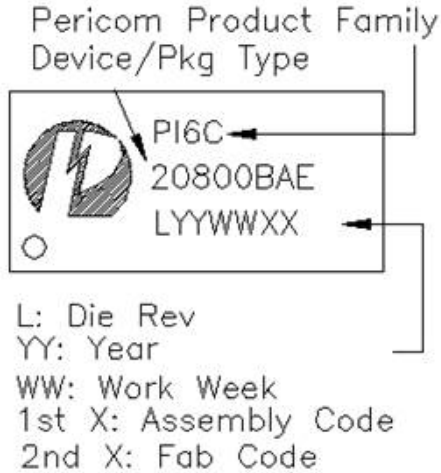


**PRODUCT CHANGE NOTICE**

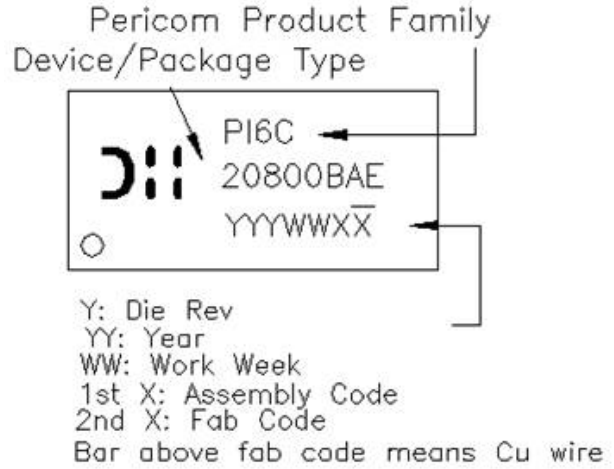
**PCN-2327 REV 2 - FINAL**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
April 20, 2018	November 11, 2020	Analog	Fab. Assembly and Test, Bond Wire Change	2327
<b>TITLE</b>				
Fab Porting from Global Foundries to MagnaChip, Assembly Site Transfer, and Bond Wire Change				
<b>DESCRIPTION OF CHANGE</b>				
<p>This PCN is being issued as a follow-up to the prior advance PCN to notify customers that Global Foundries in Woodlands, Singapore closed their 0.35um technology wafer production on December 15, 2018 and the parts listed in Table 1 are affected. Diodes will continue supporting orders for Global Foundries parts up to October 31, 2020 plus one (1) year for last time shipments.</p> <p>In order to ensure continuity of supply, Diodes will port affected products to Magnachip Semiconductor located in Heungdeok-gu, Korea using 0.18um technology. Assembly and test will also be transferred from OSE in Kaohsiung, Taiwan to Greatek Electronics Inc. in Miaoli, Taiwan. Bond wires will be changed from gold to copper wires. Any packages that have Pericom logo top marking will be changed to Diodes logo during the porting (see marking diagram below).</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers. There is no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification / reliability report (embedded in this file).</p> <p>Rev 2:</p> <ul style="list-style-type: none"><li>Added assembly/test site transfer, bond wire change, and top marking diagram.</li><li>Several part numbers were removed from Table 1 (strike through text) since they have been discontinued (EOL) via PCN-2411 or PCN-2415 in the meanwhile.</li></ul>				
<b>IMPACT</b>				
Continuity of Supply. We anticipate no impact to product's functionality and no change in product datasheet.				
<b>PRODUCTS AFFECTED</b>				
See Table 1 below for affected products				
<b>WEB LINKS</b>				
Manufacturer's Notice:	<a href="https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/">https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/</a>			
For More Information Contact:	<a href="http://www.diodes.com/contacts.html">http://www.diodes.com/contacts.html</a>			
Data Sheet:	<a href="http://www.diodes.com/catalog">http://www.diodes.com/catalog</a>			
<b>DISCLAIMER</b>				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

**Previous Top Marking**



**New Top Marking**



<b>Table 1 – Affected Part List (Fab, Assembly and Test, Bond Wire)</b>	
PI6C20800BAEX	<del>PI6C20800BAE</del>
PI6C20800BIAEX	<del>PI6C20800BIAE</del>
PI6C20800SAEX	<del>PI6C20800SAE</del>
PI6C20800SIAEX	<del>PI6C20800SIAE</del>
PI6C20800SVEX	<del>PI6C20800SIVE</del>
	<del>PI6C20800SIVEX</del>
	<del>PI6C20800SVE</del>
	<del>PI6C20800VE</del>
	<del>PI6C20800VEX</del>